

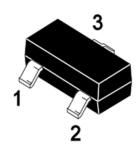
SSC8134GS6

N-Channel Enhancement Mode MOSFET

> Features

| V _{DS} | V _{GS} | R _{DS(ON)} Typ. | ID |
|-----------------|-----------------|--------------------------|------|
| | | 23mΩ@10V | |
| 30V | \pm 12V | 25mΩ@4V5 | 6.7A |
| | | 28mΩ@2V5 | |

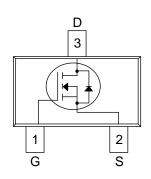
Pin configuration



<u>SOT-23</u>

> Description

This device uses advanced trench technology to provide excellent RDSON and low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.



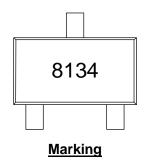
> Applications

- Intelligent Lighting
- Load Switch
- Portable Devices
- DCDC Conversion

> Ordering Information

| Device | Package | Shipping |
|------------|---------|-----------|
| SSC8134GS6 | SOT-23 | 3000/Reel |

Pin Configuration (Top View)





| Symbol | Parameter | arameter Ratings | | |
|------------------|---------------------------------------|------------------|----|--|
| Vdss | Drain-to-Source Voltage | 30 | | |
| V _{GSS} | Gate-to-Source Voltage | ±12 | V | |
| lo | Continuous Drain Current ^a | | | |
| I _{DM} | Pulsed Drain Current ^b | 26.8 | А | |
| PD | Power Dissipation ^c | 1.65 | W | |
| TJ | Operation junction temperature | -55~150 | °C | |
| Tstg | Storage temperature range | -55~150 | °C | |

> Absolute Maximum Ratings ($T_A=25^{\circ}$ unless otherwise noted)

> Thermal Resistance Ratings (T_A=25 $^{\circ}$ C unless otherwise noted)

| Symbol | Parameter | Maximum | Unit |
|--------|---|---------|------|
| Reja | Junction-to-Ambient Thermal Resistance ^a | 76 | °C/W |

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25 °C.The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}=150$ °C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

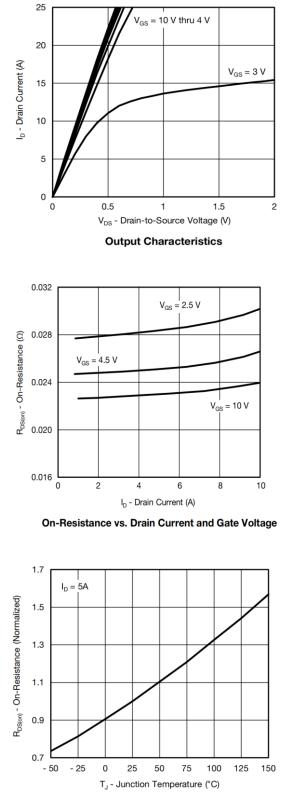


> Electrical Characteristics ($T_A=25^{\circ}C$ unless otherwise noted)

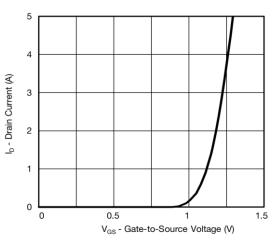
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit |
|---------------------------------|----------------------|---|------|------|------|------|
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0V, I_D = 250 \mu A$ | 30 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 uA$ | 0.6 | 0.8 | 1.2 | V |
| | R _{DS(on)} | $V_{GS} = 10V, I_D = 6A$ | | 23 | 32 | mΩ |
| Drain-Source On-Resistance | | $V_{GS} = 4.5 V, I_D = 5 A$ | | 25 | 35 | |
| | | V _{GS} = 2.5V, I _D = 4A | | 28 | 40 | |
| Zero Gate Voltage Drain Current | IDSS | $V_{DS} = 24V, V_{GS} = 0V$ | | | 1 | μA |
| Gate-Source Leak Current | lgss | $V_{GS} = \pm 12V$, $V_{DS} = 0V$ | | | ±100 | nA |
| Transconductance | G _{FS} | $V_{DS} = 5V, I_D = 2A$ | | 10 | | s |
| Forward Voltage | V _{SD} | $V_{GS} = 0V$, $I_S = 2A$ | | 0.7 | 1.3 | V |
| Input Capacitance | Ciss | | | 647 | | |
| Output Capacitance | Coss | $V_{DS} = 15V, V_{GS} = 0V,$ | | 54 | | pF |
| Reverse Transfer Capacitance | C _{RSS} | f = 1MHz | | 48 | | |
| Turn-on Delay Time | T _{D(ON)} | | | 9 | | |
| Rise Time | Tr | $V_{GS} = 10V, R_L = 2.3\Omega$ | | 13 | | ns |
| Turn-off Delay Time | T _{D(OFF)} | V_{DS} = 15V, R_G = 3 Ω | | 25 | | |
| Fall Time | T _f | | | 19 | | |
| Total Gate Charge | Q_{G} | V _{GS} = 10V, V _{DS} = 15V, | | 11 | | |
| Gate to Source Charge | Q _{GS} | | | 2.3 | | nC |
| Gate to Drain Charge | Q_{GD} | I _D = 5A | | 1.3 | | |



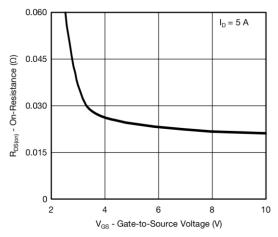
> Typical Performance Characteristics ($T_A=25^{\circ}C$ unless otherwise noted)



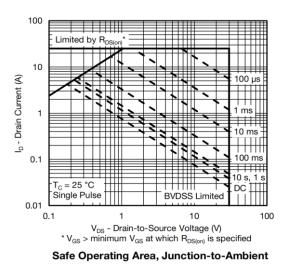
On-Resistance vs. Junction Temperature



Transfer Characteristics



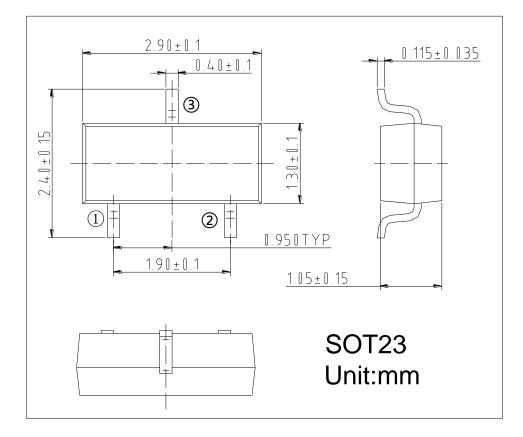
On-Resistance vs. Gate-to-Source Voltage



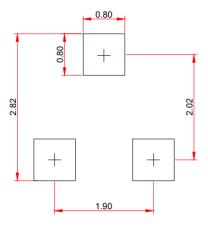
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Package Information



Recommended Pad outline (Unit: mm)





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